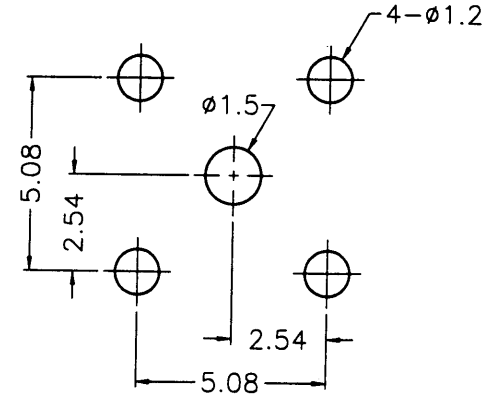
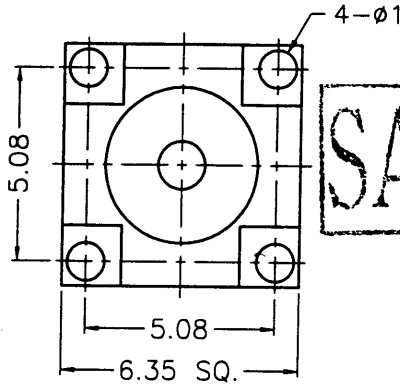
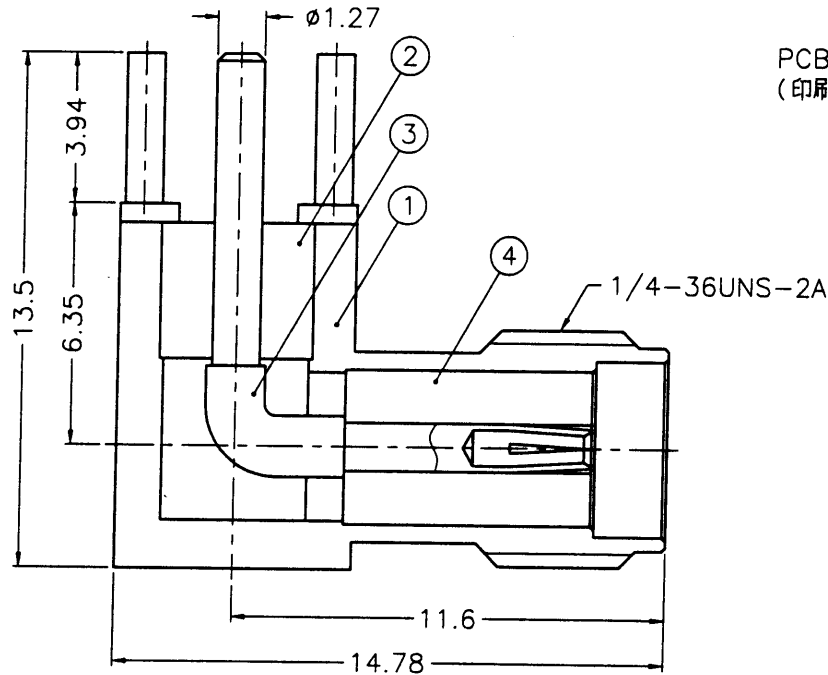


REVISIONS		
ISS	ZONE	DESCRIPTION\PER REQUEST\DATE
B	A-1	NO.4 WAS CHANGED\RD-DM89012701B\01-27-00'
C	A-1	NO.3 WAS CHANGED\RD-DM91011001K\01-10-02'
	E-7	PCB MOUNTING HOLE WAS CHANGED\N/A\09-20-02'



PCB MOUNTING HOLE
(印刷电路板架設孔)



- NOTES: FINISH (PLATING THICKNESS IN MICRO-INCHES)
- NICKEL PL. 100 MIN. THICK OVER COPPER PL. 300 MIN. THICK
 - BERYLLIUM COPPER PER QQ-C-530
 - GOLD PL. 50 MIN. THICK OVER NICKEL PL. 100 MIN. THICK OVER COPPER STRIKE
 - TEFLON MIL-P-19468
 - ZINC DIECAST

DIMENSIONS ARE IN MILLIMETERS				PART NO.	
UNLESS OTHERWISE SPECIFIED TOLERANCES				APPROVED	DATE
0.5-6 = ±0.2				<i>gawcky</i>	09-20-02'
6-30 = ±0.4				CHECKED	DATE
30-120 = ±0.6				<i>Ken</i>	09-20-02'
120-315 = ±1				DRAWN	DATE
315-1000 = ±1.6				<i>Ken</i>	09-20-02'
1000-2000 = ±2.4					
SCALE	5/1	ISSUE	C	FILE NO.	F:\DWG\SMA\6252D1\50\NT50G

Amphenol - Kai Jack	
TAINAN TAIWAN	
TITLE	SMA R/A P.C. MOUNT JACK
DRAWING NO.	KJ-SMA6252D1-NT50G-50
ITEM NO.	116252AAL66NE5F

NO.	DESCRIPTION	MATERIAL	FINISH	Q'TY	DRAWING NO.
4	INSULATOR	NOTE 4	NATURAL	1	SMA6252D1-4
3	CONTACT PIN	NOTE 2	NOTE 3	1	SMA6252A2-4-B
2	INSULATOR	NOTE 4	NATURAL	1	SMA7790-5T-50
1	BODY	NOTE 5	NOTE 1	1	SMA6252D1-1

7RD-DR 6575 8